- Four J-K Flip-Flops in a Single Package . . .
 Can Reduce FF Package Count by 50%
- Common Positive-Edge-Triggered Clocks with Hysteresis . . . Typically 200 mV
- Fully Buffered Outputs
- Typical Clock Input Frequency . . . 45 MHz

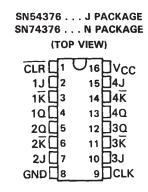
description

These quadruple TTL J-K flip-flops incorporate a number of third-generation IC features that can simplify system design and reduce flip-flop package count by as much as 50%. They feature hysteresis at the clock input, fully buffered outputs, and direct clear capability. The positive-edge-triggered SN54376 and SN74376 are directly compatible with most Series 54/74 MSI registers.

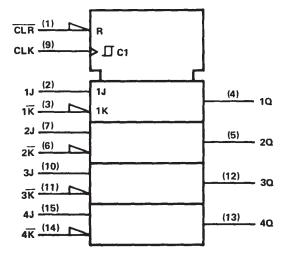
The SN54376 is characterized for operation over the full military temperature range of -55° C to 125° C; the SN74376 is characterized for operation from 0° C to 70° C.

FUNCTION TABLE (EACH FLIP-FLOP)

COMMON INPUTS		INPUTS		OUTPUT	
CLEAR	CLOCK	J K		α	
L	Х	X	Х	L	
Н	†	L	Н	α_0	
Н	†	Н	Н	н	
н	†	L	L	L	
н	†	ј.н	L	TOGGLE	
Н	L	×	Х	α_0	

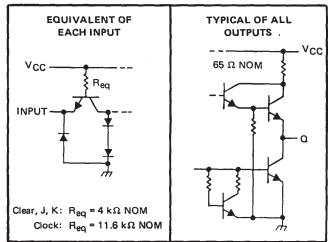


logic symbol†



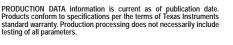
[†]This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

schematics of inputs and outputs



Resistor values shown are nominal.

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)	/ V
Input voltage	
Operating free-air temperature range: SN54376	-55°C to 125°C
SN74376	
Storage temperature range	

NOTE 1: Voltage values are with respect to network ground terminals.

recommended operating conditions

		SN54376			SN74376			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	ONT
Supply voltage, V _{CC}		4.5	5	5.5	4.75	5	5.25	V
High-level output current, IOH				-800			-800	μΑ
Low-level output current, IOL				16			16	mA
Clock frequency		0		30	0		30	MHz
Pulse width, t _W	Clock high	22			22			
	Clock low	12			12			ns
	Preset or clear low	12			12			
Setup time, t _{su}	J, K inputs	01			01			ns
	Clear inactive state	101			101			113
Input hold time, th		201			20↑			ns
Operating free-air temperature, TA		- 55		125	0		70	°C

^{↑↓}The arrow indicates the edge of the clock pulse used for reference: ↑ for the rising edge, ↓ for the falling edge,

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS†		MIN	TYP‡	MAX	UNIT
VIH	High-level input voltage			2			V
VIL	Low-level input voltage					0.8	V
VIK	Input clamp voltage	V _{CC} = MIN,	I _I = -12 mA			-1.5	V
V _{OH}	High-level output voltage	V _{CC} = MIN, V _{IL} = 0.8 V,	V _{1H} = 2 V, I _{OH} = -800 μA	2.4	3,4		V
VOL	Low-level output voltage	V _{CC} = MIN, V _{IL} = 0.8 V,	V _{IH} = 2 V, I _{OL} = 16 mA		0.2	0.4	٧
11	Input current at maximum input voltage	V _{CC} = MAX,	V _I = 5.5 V			1	mA
Iн	High-level input current	V _{CC} = MAX,	V _I = 2.4 V			40	μΑ
TIL	Low-level input current	V _{CC} = MAX,	V ₁ = 0.4 V			-1.6	mA
los	Short-circuit output current§	V _{CC} = MAX		-30		85	mA
Icc	Supply current	V _{CC} = MAX			52	74	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
f _{max}	Maximum clock frequency	C: - 15 oF	30	45		MHz
tPHL	Propagation delay time, high-to-low-level output from clear	— C _L = 15 pF, — R _L = 400 Ω,		17	30	ns
tPLH	Propagation delay time, low-to-high-level output from clock	See Note 2		22	35	ns
tPHL	Propagation delay time, high-to-low-level output from clock	See Note 2		24	35	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



 $[\]ddagger$ All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[§]Not more than one output should be shorted at a time.

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